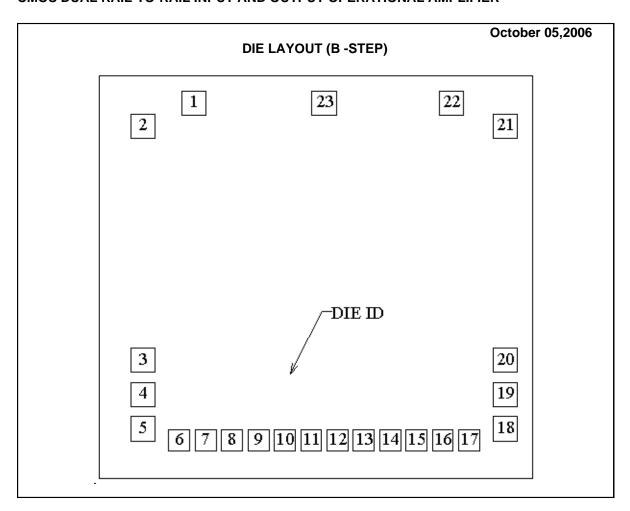


LMC6482AI MDA MWA CMOS DUAL RAIL-TO-RAIL INPUT AND OUTPUT OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

ILI WILL SID AUTO I LINGTION							
Fabrication Attributes		General D	General Die Information				
Physical Die Identification	LMC6482B	Bond Pad Opening Size (min)	100μm x 100μm				
Die Step	В	Bond Pad Metalization	ALUMINUM				
Phys	Physical Attributes		VOM NITRIDE				
Wafer Diameter	150mm	Back Side Metal	Bare Back				
Die Size (Drawn)	1641μm x 1768μm 64.6mils x 69.6mils	Back Side Connection	Floating				
Thickness	330µm Nominal						
Min Pitch	107μm Nominal						

Special Assembly Requirements:	
Note: Actual die size is rounded to the nearest micron.	



LMC6482AI MDA MWA

CMOS DUAL RAIL-TO-RAIL INPUT AND OUTPUT OPERATIONAL AMPLIFIER

WOS DUAL RAIL-	TO-RAIL INPUT AN	D OUTPUT O	PERATIONAL	LAMPLIF	IEK	
	Die Bond Pad	Coordinate I	Locations (B	-Step)		
(Reference	d to die center, coordin	nates in µm) <mark>N</mark> (C = No Connect	tion, N.U.	= Not U	Jsed
SIGNAL	PAD#	X/Y COORDINATES PAD SIZE				
NAME	NUMBER	X	Υ	Х		<u>Y</u>
OUTA	1	-500	714	100	х	100
IN A -	2	-709	619	100	Χ	100
IN A +	3	-709	-340	100	Χ	100
NC	4	-709	-480	100	X	100
V -	5	-709	-620	100	Χ	100
NC	6	-560	-667	86	X	86
NC	7	-452	-667	86	X	86
NC	8	-344	-667	86	X	86
NC	9	-236	-667	86	X	86
NC	10	-128	-667	86	X	86
NC	11	-20	-667	86	X	86
NC	12	88	-667	86	X	86
NC	13	196	-667	86	X	86
NC	14	304	-667	86	X	86
NC	15	412	-667	86	X	86
NC	16	520	-667	86	X	86
NC	17	628	-667	86	X	86
NC	18	777	-620	100	X	100
NC	19	777	-480	100	X	100
INB+	20	777	-340	100	Х	100
INB-	21	777	619	100	Х	100
OUT B	22	555	714	100	Х	100
V +	23	34	714	100	Х	100



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